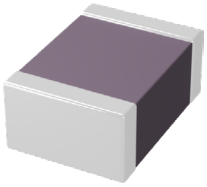
APPLICATIONS

- Lasers, CATV, RF Power Amplifiers
- Mixers, RF Instruments



RoHS compliant

ELECTRICAL PARAMETERS

ELECTRICAL CHARACTERISTICS:
at + 25°C unless otherwise specified

OPERATING TEMPERATURE:
- 55°C, + 125°C

TEMPERATURE COEFFICIENT:
± 30ppm

DISSIPATION FACTOR:
≤ 5.10^{-4} at 1Vrms at 1Vrms 1MHz for values ≤ 1000pF
≤ 5.10^{-4} at 1Vrms at 1Vrms 1KHz for values > 1000pF

INSULATION RESISTANCE (IR):
25°C/Un 10^5 MOhm or 1000 Ohm-Farad whichever is less
125°C/Un 10^4 MOhm or 100 Ohm-Farad whichever is less

DIELECTRIC STRENGTH TEST:
Performed per method 103 of EIA 198-2-E
Applied test voltages :
200Vdc-rated : 250% of rated voltage
500Vdc-rated : 200% of rated voltage

QUICK REFERENCE DATA

	0505	1111	2525	4040
MIN	0.1pF	0.3pF	1pF	1pF
200V	100pF			
250V	56pF		2.2nF	
300V		1nF		
500V		680pF	1.2nF	4.7nF
630V		470pf		
1000V		180pF	1.2nF	2.2nF
1500V		100pF		
2000V			470pF	1nF
3000V			270pF	470pF
4000V			180pF	
5000V			100pF	180pF
7200V				100pF

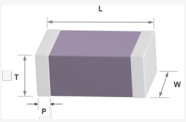
ORDERING INFORMATION

2525	Q	560	F	E	X	B	-
SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINATION	PACKAGING	SPECIAL
0505 1111 2525 4040	Q = High Q	Expressed in picofarads (pF).The first two digits are significant, the third digit gives the number of noughts. Example : 102 = 1000pF	A = ±0.05pF if < 10pF and 0.05% if > 10pF B = ± 0.1pF C = ± 0,25pF D = ± 0,5pF F = ± 1% G = ± 2% J = ± 5%	C = 200V P = 250V D = 300V E = 500V F = 630V G = 1000V O = 1500V H = 2000V I = 3000V K = 4000V L = 5000V S = 7200V	X = Nickel Tin C = Copper Tin (Non magnetic) H = Dipped SnPb I = Electrolytic SnPb Q = Solderable Silver	B = Reel V = Bulk	- Dxx = Reliability spec Exx = Sorting spec

This document is subject to change without notice.

DIMENSIONS IN MILIMETERS

Designation		0505	1111	2525	4040
LENGTH (L)		1.40 ± 0.6	3 ± 0.7	6.35 +0.5/-0.8	10.2 ± 1.00
WIDTH (W)		1.40 ± 0.4	2.8 ± 0.8	6.35 ± 0.4	10.2 ± 1.00
THICKNESS (T)		1.45	2.6	2.6	6.00
TERMINATION (P)	MIN	0.10	0.30	0.25	0.80
	MAX	0.40	0.50	0.80	1.50



For P termination (Polymer type) add 0.20mm to all dimensions.

STANDARD SIZE : 0505 TO 4040

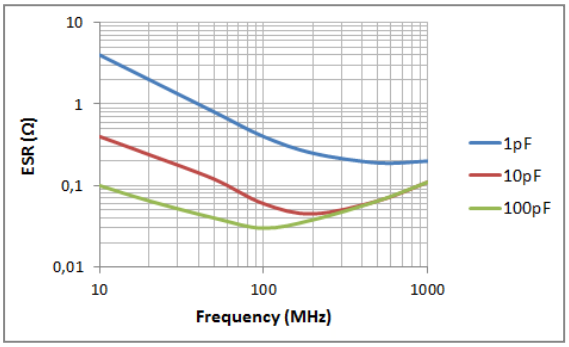
SIZE		0505		1111					2525							4040					
CODE	CAP	200	250	300	500	630	1000	1500	250	500	1000	2000	3000	4000	5000	500	1000	2000	3000	5000	7200
1R0	1pF																				
1R2	1.2pF																				
1R5	1.5pF																				
1R8	1.8pF																				
2R2	2.2pF																				
2R7	2.7pF																				
3R3	3.3pF																				
3R9	3.9pF																				
4R7	4.7pF																				
5R6	5.6pF																				
6R8	6.8pF																				
8R2	8.2pF																				
100	10pF																				
120	12pF																				
150	15pF																				
180	18pF																				
220	22pF																				
270	27pF																				
330	33pF																				
390	39pF																				
470	47pF																				
560	56pF																				
680	68pF																				
820	82pF																				
101	100pF																				
121	120pF																				
151	150pF																				
181	180pF																				
221	220pF																				
271	270pF																				
331	330pF																				
391	390pF																				
471	470pF																				
561	560pF																				
681	680pF																				
821	820pF																				
102	1nF																				
122	1.2nF																				
152	1.5nF																				
182	1.8nF																				
222	2.2nF																				
272	2.7nF																				
332	3.3nF																				
392	3.9nF																				
472	4.7nF																				
562	5.6nF																				
682	6.8nF																				
822	8.2nF																				

This document is subject to change without notice.

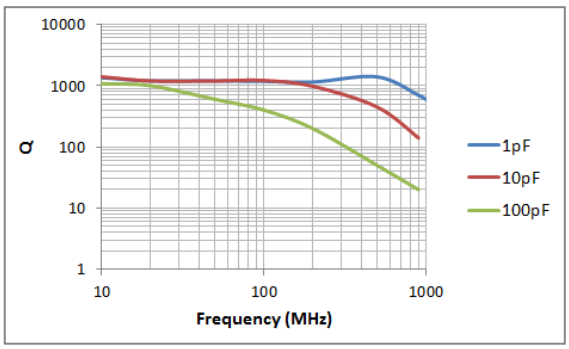
TYPICAL CHARACTERISTICS : 0505 TO 1111

0505

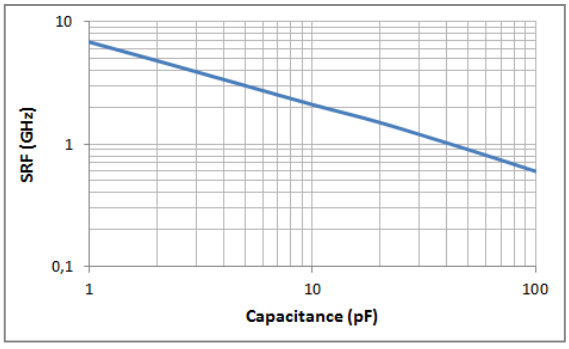
ESR = f(F_{MHz})



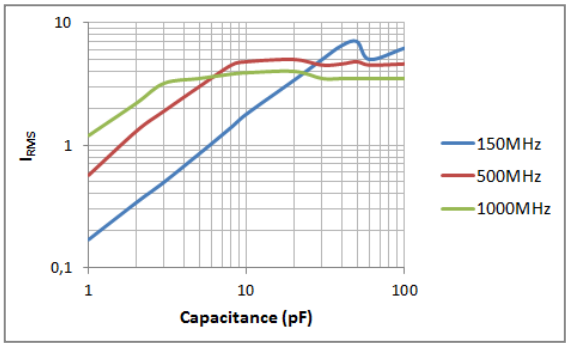
Q Value = f(F_{MHz})



Resonant Frequency = f(CAP_{pF})

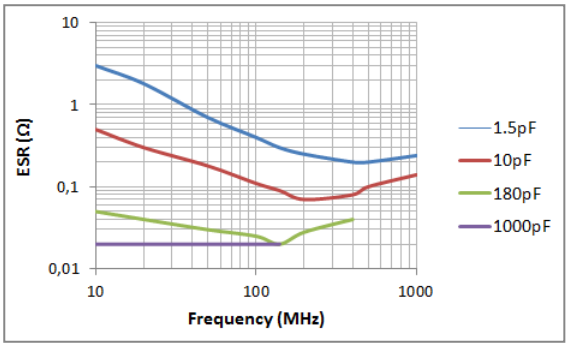


I_{RMS} = f(CAP_{pF})

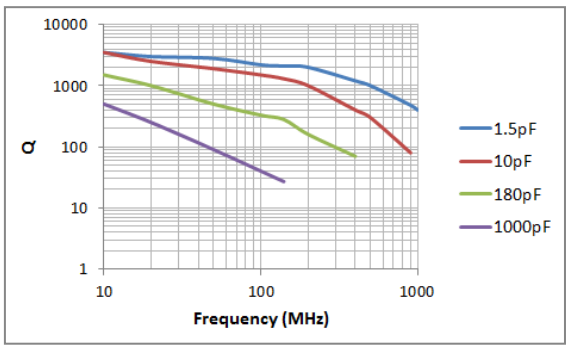


1111

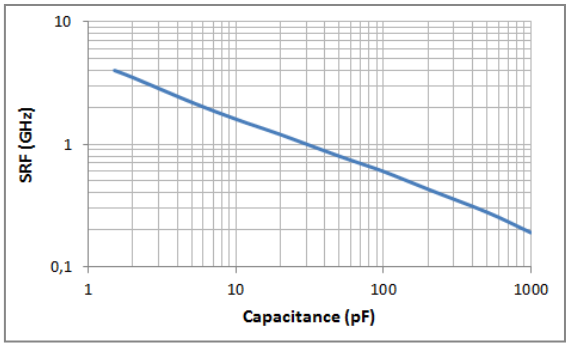
ESR = f(F_{MHz})



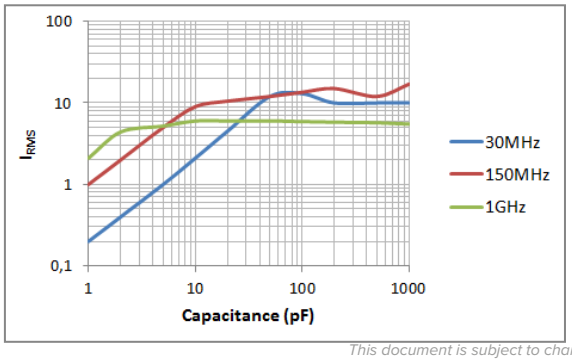
Q Value = f(F_{MHz})



Resonant Frequency = f(CAP_{pF})



I_{RMS} = f(CAP_{pF})

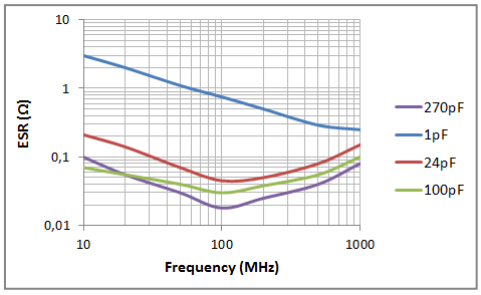


This document is subject to change without notice.

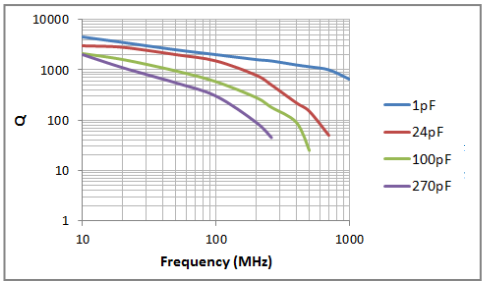
TYPICAL CHARACTERISTICS : 2525 TO 4040

2525

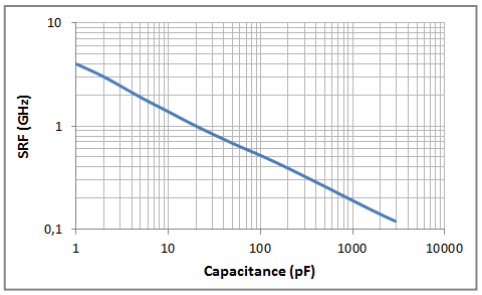
ESR = f(F_{MHz})



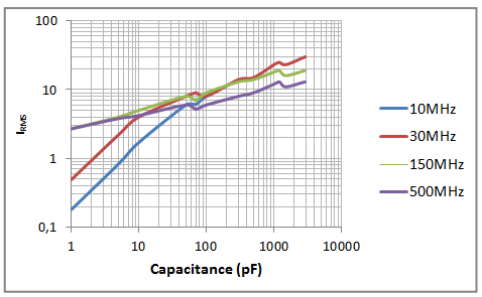
Q Value = f(F_{MHz})



Resonant Frequency = f(CAP_{pF})

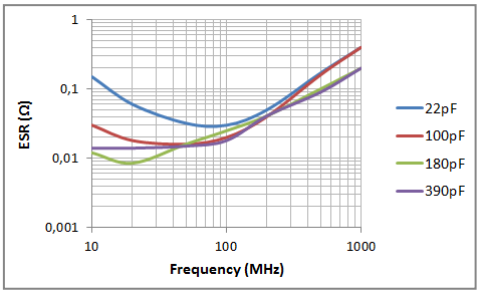


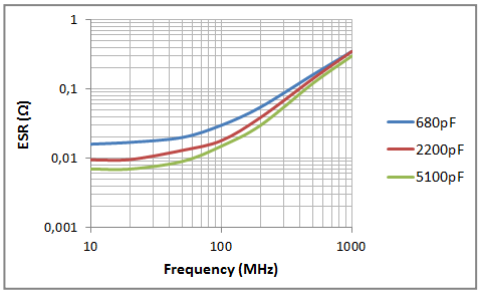
I_{RMS} = f(CAP_{pF})



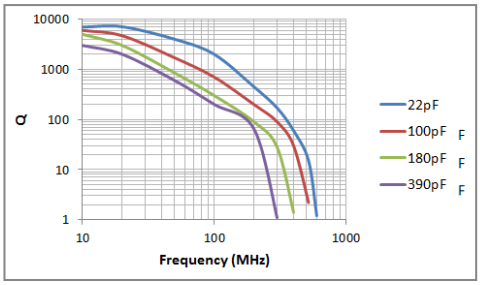
4040

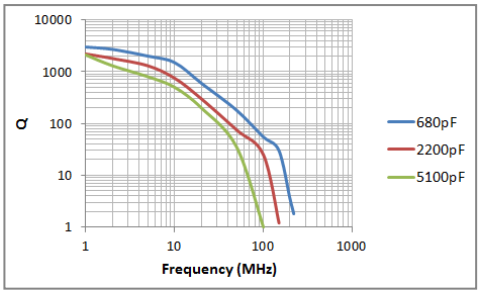
ESR = f(F_{MHz})



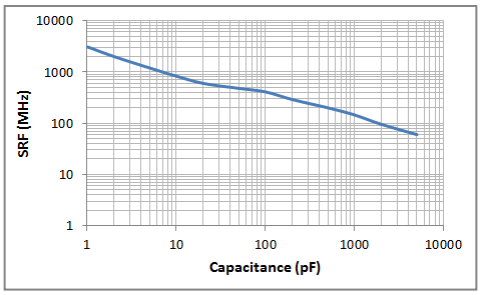


Q Value = f(F_{MHz})

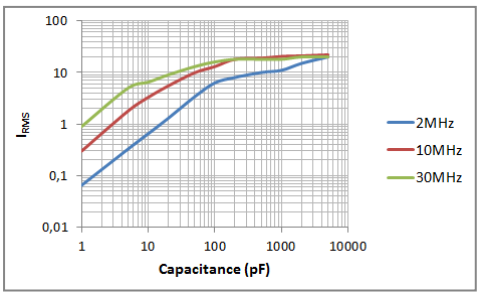




Resonant Frequency = f(CAP_{pF})



I_{RMS} = f(CAP_{pF})



This document is subject to change without notice.

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :
Indoors under 5 ~ 40°C and 20% ~ 70% RH.
No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.
Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as possible. Taped products should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 24 months after shipment. Extended shelf life over this period requires a solderability check before use.

HANDLING

Chip capacitors are made of dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chips Capacitors should be handled with care to avoid contamination or damage. The use of vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat process is required.
The rate of preheat should not exceed 3°C per second.

SOLDERING FLUX

Use mildly activated rosin RA and RMA fluxes, but do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

SOLDERING TYPE

Leads containing solders, such as Sn60, Sn62 or Sn63 and lead free solders, such as SnAgCu, can all be used with our MLCCs.
In case of non-magnetic termination code “C”, use leads containing or lead (Pb)-free SAC305 solders.

SOLDERING HEIGHT

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.
(Reference from IPC-610E)

COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

CLEANING

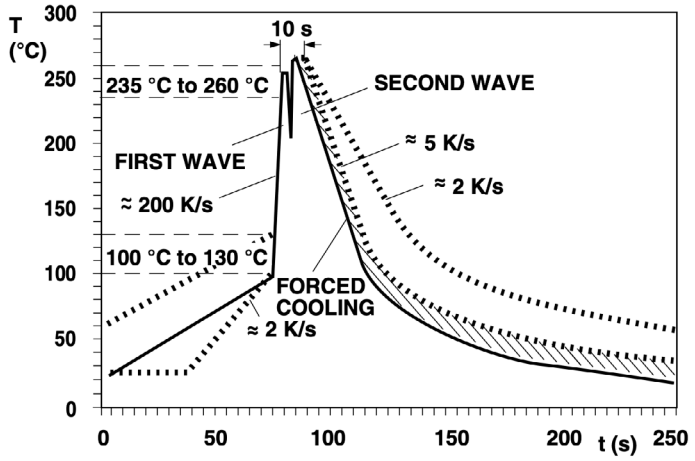
All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvents. The choice of the proper system depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability for the cleaning system to remove flux residues and contamination from under the chips is of paramout importance.

SOLDERING CONDITIONS

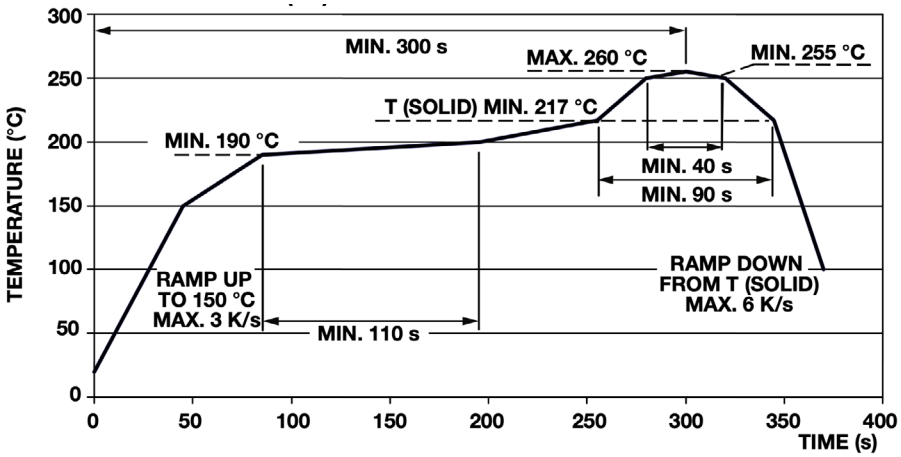
SIZE	THICKNESS	WAVE	REFLOW
0402	All	O	O
0505	All	O	O
0603	All	O	O
0805	< 1.25mm	O	O
0805	≥ 1.25mm		O
1111	< 1.25mm	O	O
1111	≥ 1.25mm		O
1206	< 1.25mm	O	O
1206	≥ 1.25mm		O
1210	< 1.25mm	O	O
1210	≥ 1.25mm		O
larger than 1210	All		O

This document is subject to change without notice.

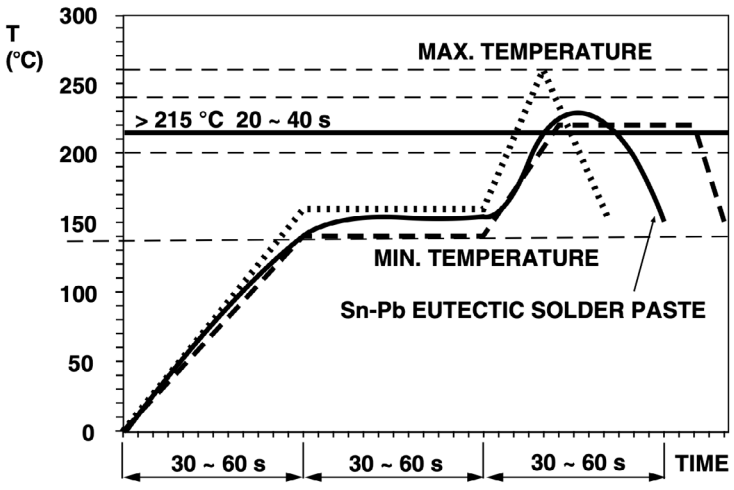
WAVE SOLDERING PROFILE



LEADFREE REFLOW SOLDERING PROFILE

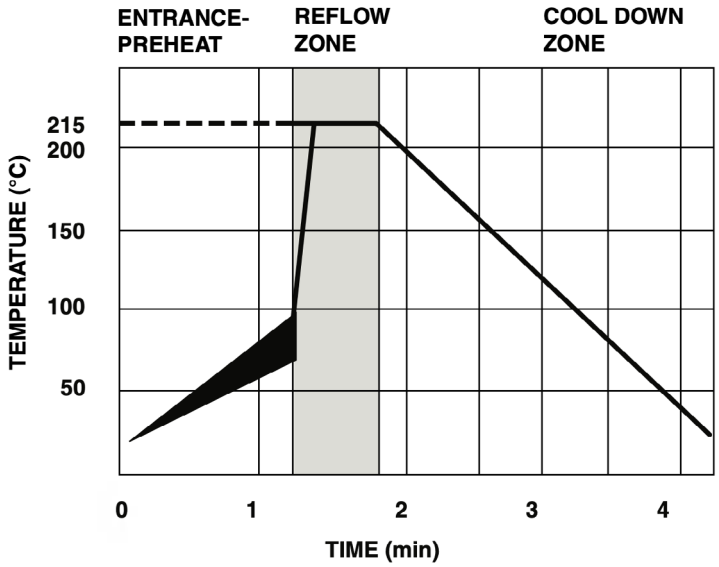


SNPB REFLOW SOLDERING PROFILE



This document is subject to change without notice.

VAPOUR PHASE REFLOW PROFILE



HAND SOLDERING

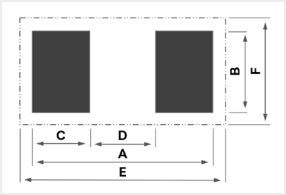
Hand soldering is not recommended as the thermal shock may cause a crack, however if used the following recommendations should be taken :

- Soldering iron tip diameter ≤3.0 mm and wattage max. 20W.
- The Capacitors shall be pre-heated to 150°C and the temperature gradient between the devices and the tip of the soldering iron.
- Tip temperature should be ≤280°C and should't be applied for more than 5 seconds.
- The required amount of solder shall be melted on the soldering tip.
- The tip of iron should not contact the ceramic body directly.
- The Capacitors shall be cooled gradually at room temperature after soldering.
- Forced air cooling is not allowed.

This document is subject to change without notice.

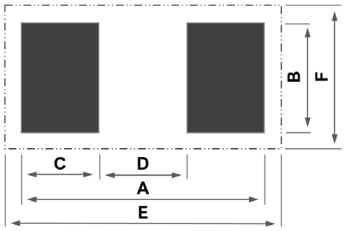
TYPICAL SMD FOOTPRINT WAVE SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN MM					
	A	B	C	D	E	F
0603	2.40	0.80	0.70	1.00	3.10	1.40
0805	3.20	1.30	0.90	1.40	4.10	1.85
1206	4.80	1.70	1.25	2.30	5.90	2.25
1210	4.80	2.60	1.25	2.30	5.90	3.15



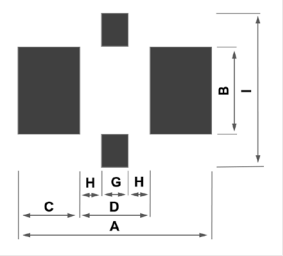
TYPICAL SMD FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm					
	A	B	C	D	E	F
0201	0.65	0.30	0.21	0.23	0.90	0.60
0204	1.00	1.00	0.30	0.40	1.25	1.45
0402	1.50	0.50	0.40	0.70	1.75	0.95
0306	1.30	1.60	0.40	0.50	1.55	2.05
0404	1.50	1.00	0.40	0.70	1.75	1.45
0504	1.90	1.00	0.40	1.10	2.15	1.45
0505	1.90	1.30	0.50	0.80	2.15	1.75
0508	1.90	2.00	0.50	0.90	2.15	2.55
0603	2.30	0.80	0.60	1.10	2.55	1.35
0612	2.30	3.20	0.60	1.10	2.55	3.75
0805	2.90	1.25	0.90	1.10	3.15	1.80
1206	4.10	1.60	0.90	2.30	4.35	2.25
1210	4.10	2.50	1.00	2.10	4.35	3.15
1808	5.50	2.10	1.20	3.10	5.75	2.75
1812	5.50	3.30	1.20	3.10	5.75	3.95
1825	5.50	6.55	1.20	3.10	5.75	7.20
2211	6.80	3.00	1.40	4.00	7.05	3.65
2220	6.80	5.40	1.40	4.00	7.05	6.05
2225	6.80	6.70	1.65	3.50	7.05	7.50
2525	7.70	6.75	1.65	4.40	7.95	7.55
2825	8.40	6.70	1.65	5.10	8.65	7.50
3033	9.00	8.80	1.95	5.10	9.25	9.60
3640	10.55	10.70	2.35	5.85	10.80	11.50
4040	11.60	10.70	2.35	6.90	11.85	11.50
40100	11.60	26.20	2.35	6.90	11.85	27.00
5550	15.50	13.20	2.35	10.80	15.75	14.00
6080	16.70	20.80	2.35	12.00	16.95	21.60
6660	18.30	15.70	2.35	13.60	18.55	16.50
8060	21.90	15.70	2.35	17.20	22.15	16.50
80150	21.90	38.90	2.35	17.20	22.15	39.70



TYPICAL FILTER FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm						
	A	B	C	D	G	H	I
0603	2.30	0.80	0.45	1.40	0.60	0.40	1.50
0805	2.90	1.25	0.90	1.80	0.80	0.50	2.00
1206	4.10	1.60	0.90	2.40	1.00	0.70	3.00
1806	5.50	1.60	1.20	3.20	1.00	1.10	3.00
1812	5.50	3.30	1.20	3.90	1.50	1.20	4.80
2220	6.80	5.40	1.40	4.50	1.50	1.50	7.00

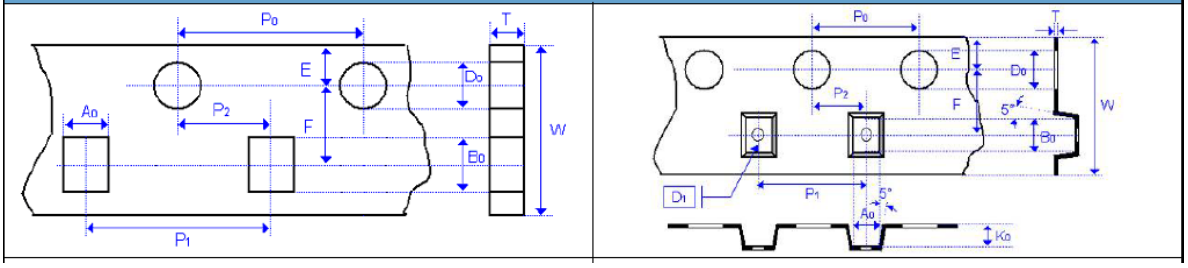


This document is subject to change without notice.

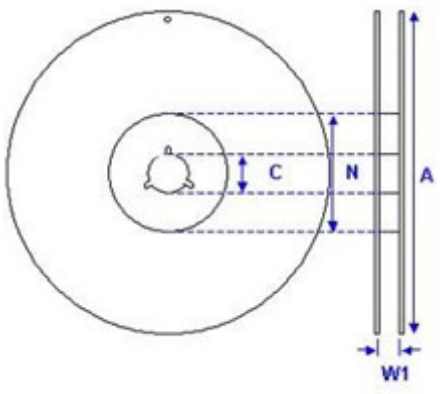
PACKAGE DIMENSION AND QUANTITY

SIZE	THICKNESS	PAPER TAPE		PLASTIC TAPE	
		7" REEL	13" REEL	7' REEL	13" REEL
0402	0.5 ± 0.05	10 K	50 K		
0504	0.6 ± 0.05			4K	15K
	0.9 ± 0.05			4K	15K
0603	0.7 ± 0.07	4K		4K	15K
	0.9 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	15K
	1.1 ± 0.07			4K	15K
0805	0.8 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	10K
	1.1 ± 0.07			3K	10K
	1.3 ± 0.07			3K	10K
1206	1.1 ± 0.1			3K	10K
	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			2K	8K
1210	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			1K	6K
1808	1.4 ± 0.1			3K	8K
1812	1.6 ± 0.1			2K	8K
	2.1 ± 0.1			1K	6K
	2.8 ± 0.1			1K	6K
2220	1.8 ± 0.1			1K	6K
	3.0 ± 0.1			0.5K	2K
2225	3.0 ± 0.1			0.5K	2K
3033	3.0 ± 0.1			0.5K	2K
3640	3.0 ± 0.1			0.5K	2K
5440	3.9 ± 0.1				0.5K - 1K

EMBOSSED TAPE DIMENSIONS



REEL SIZE	7"	7"	13"
C	13.0 +0.5/-0.2	13.0 +0.5/-0.2	13.0 +0.7/-0.3
W1	8.4 +1.5/-0	12.4 +2.0/-0	8.4 +2.0/-0
A	178.0 ±0.10	178.0 ±0.10	330.0 ±1.0
N	60.0 ±1.0	80.0 ±1.0	100 ±1.0



This document is subject to change without notice.

RELIABILITY PRINCIPLES OVERVIEW

In order to guarantee highly reliable products to their customers, SRT-Microcéramique follows a strict quality policy which is explained below :

- According to AECQ philosophy, each component belongs to a family, in which the most restrictives members (four corners) have been fully qualified.
- PME components are produced in our Vendôme facility, with very stable process and equipments, in order to ensure reliability and reproductibility.
- Reliability is based on batch tests, new product or equipment-specific qualifications and periodic requalifications.
- In addition to those regular tests, our quality departement launches regular accelerated tests to further deepen our reliability datas.
- Tests and qualifications of our standard products are based on AECQ methodology and are qualified according to the following limits.
- In accordance to AECQ methodology, specifics tests and limits can be adapted to fit our clients' needs.
- A whole range of stricter reliability tests can be offered for high Reliability products (burn-in, shocks, pulses...) for medical, space and defense applications.
- Based on our reliability database, FIT datas can be provided if necessary.

TESTING

Tests conducted during each batch

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
100%	Capa, DF, IR	CECC-32100-4.6		according to datasheet
100%	Visual	CECC-32100-4.5	AEC-Q200-9	no visual defects
50/batch	DPA		AEC-Q200-5	internal component integrity
5/batch	Dimension	CECC-32100-4.5	AEC-Q200-5	according to datasheet
5/batch	Resistance to soldering heat	CECC-32100-4.10	AEC-Q200-15	
5/batch	Solderability	CECC-32100-4.11	AEC-Q200-18	
10/batch	Voltage proof	CECC-32100-4.6.4		
1/ceramic batch	Temperature coefficient	CECC 32100-Prgph4,7		according to datasheet

QUALIFICATIONS

Each component family has been qualified according to CECC and AECQ tests methodology, which are renewed on a periodic basis.

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
Qualif	Electrical Characterization	CECC-32100-4.6 4.7	AEC-Q200-19	measure before test according to datasheet and after test according to post environmental limits
Qualif	Temperature Cycling	JESD22 Method-JA method 104	AEC-Q200-4	1,000 cycles -55°C to +125°C Measurement at 24 ± 2 hours after test conclusion
Qualif	Biased Humidity	MIL-STD-202 Method 103	AEC-Q200-7	1,000 hours 85°C/85%RH. Rated voltage. Measurement at 24 ± 2 hours after test conclusion
Qualif	Operational Life	MIL-STD-202 Method 108 condition D	AEC-Q200-8	1,000 hours at 125°C with apllied Voltage : 2xRV RV≤500V, 1.2xRV 500V<RV≤1250V, RV RV>1250V
Qualif	High Temperature Exposure (Storage)	MIL-STD-202 Method 108	AEC-Q200-3	1,000 hours at 150°C with 0V. Measurement at 24 ± 2 hours after test conclusion
Qualif	Terminal Strength	CECC-32100-4.8	AEC-Q200-6	1.8kg 60 seconds
Qualif	Vibration	MIL-STD-202 Method 204	AEC-Q200-14	5g 20min 12cycles 3 orientations 10-2000Hz
Qualif	Board Flex	CEC 32100-4.9	AEC-Q200-21	3mm Type 1, 2mm Type 2, Measurement at 24 ± 2 hours after test conclusion

POST ENVIRONMENTAL STRESS LIMIT

DIELECTRIC	DISSIPATION FACTOR (MAXIMUM)	CAPACITANCE SHIFT	INSULATION RESISTANCE
NPO	≤ 4 10-3	±2%	10% initial limit
N2T	≤ 6 10-3	±4%	10% initial limit
X7R	≤ 0.035	±15%	10% initial limit

This document is subject to change without notice.

REACH Compliance

- SRT-Microcéramique delivers non-chemical articles only.
- These contain no substances which are intented to be released under normal or reasonably foreseeable conditions of use according Reach article 7(1).

SRT-Microcéramique confirms hereby that our products contain none of the substances which are listed in the present candidate list of the European Chemicals Agency (ECHA), above a concentration of 0.1% by weight of the whole component.

Candidate list of substances (European Chemicals Agency ECHA) :
http://echa.europa.eu/fr/candidate-list-table

ROHS COMPLIANCE

SRT-Microcéramique herewith confirms that RoHS-compliant SRT-microcéramique products are conforming to the following EU directives:
EU directive 2015/863/EU EU directive 2011/65/EU EU directive 2003/11/EC

Following restricted materials are not used and do not exceed the legal limits: Lead (Pb, see exemptions),
- Mercury (Hg)
- Cadmium (Cd)
- Chromium (Cr VI)
- Polybrominated biphenyls (PBB) Polybrominated diphenyl ethers (PBDE) Bis(2-Ethylhexyl) phtalate (DEHP) Benzyl butyl phtalate (BBP)
- Dibutyl phtalate (DBP) Diisobutyl phtalate (DIBP)

Exemptions: The following exemptions according to the RoHS appendit are applicable:
Identity 7(a) :
- Lead in high melting temperature type solders (i.e lead-based alloys containing 85% by weight or more lead).

Identity 7(c)-I :
- Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

The components are suitable for a lead-free process according to EN 60068-2-58 and in accordance with the IPC/JEDEC standard J-Std-020D.
The lead free process has been tested using solder alloy ***Sn*** 96.5 ***Ag*** 3 ***Cu*** 0.5

Export controls and dual-use regulations

Some SRT-Microcéramique components fall under 'dual-use' items under international export controls definition - those that can be used for civil or military purposes which meet certain specified technical standards.

The defining criteria for a dual use component is one with a voltage rating of >750Vdc and a capacitance value of >250nF when measured at 750Vdc and a series inductance <10nH. Components defined as dual-use under the above criteria may require a licence for export across international borders. Please contact us for further information on specific part numbers.

ISO9001:2015

In their design, research and development as well as the manufacturing of MLCC capacitors, customer service and distribution SRT-Microcéramique uses and maintains a Management System audited and certified in accordance to : **ISO9001:2015**

You may contact us for any inquiry regarding the regulations and compliance listed above.

This document is subject to change without notice.